20. A clamping system for securing a semiconductor device during a bonding operation, the clamping system comprising:

a device clamp including a body portion, the body portion including a lower surface configured to contact a semiconductor device during a bonding operation, the lower surface defining a constraining feature for constraining at least a portion of the semiconductor device during the bonding operation; and

a support structure for supporting the semiconductor device from below during the bonding operation, wherein the support structure includes a compliant layer.

21. The clamping system of claim 20 wherein the body portion including the lower surface is formed from a unitary piece of material.

22. The clamping system of claim 20 wherein the lower surface is separate from, and secured to, the remainder of the body portion.

~~23. The clamping system of claim 20 further comprising a support structure for supporting the semiconductor device from below during the bonding operation.~~

~~24. The clamping system of claim 23 wherein the support structure includes a compliant layer.~~

~~25~~23. The clamping system of claim ~~24~~ 20 wherein the support structure includes an upper layer configured for contacting the semiconductor device, the compliant layer being below the upper layer.

~~26~~24. The clamping system of claim ~~25~~ 23 wherein the support structure includes a base, the compliant layer being positioned between the base and the upper layer.

~~27~~25. The clamping system of claim 20 wherein the constraining feature includes a raised portion defined by the lower surface to constrain the portion of the semiconductor device during the bonding operation.

~~28~~26. The clamping system of claim ~~27~~ 25 wherein the raised portion includes substantially parallel raised features to constrain the portion of the semiconductor device during the bonding operation.

~~29~~27. The clamping system of claim ~~27~~ 25 wherein the raised portion defines a valley to constrain the portion of the semiconductor device during the bonding operation.

~~30~~28. The clamping system of claim ~~27~~ 25 wherein the raised portion includes a plurality of wall portions to at least partially surround, and thereby constrain, the portion of the semiconductor device during the bonding operation.

~~31~~29. The clamping system of claim ~~27~~ 25 wherein the semiconductor device includes a leadframe, and wherein the portion of the semiconductor device constrained by the raised feature includes a portion of the leadframe.

~~32~~30. The clamping system of claim ~~31~~ 29 wherein the portion of the leadframe constrained by the raised feature includes at least one of a lead, a tie bar, a heat sink, and a die paddle of the leadframe.

~~33~~31. The clamping system of claim 20 wherein the semiconductor device includes a leadframe, and wherein the portion of the semiconductor device constrained during the bonding operation by the constraining feature includes a portion of the leadframe.

~~34~~32. The clamping system of claim ~~33~~ 31 wherein the portion of the leadframe constrained by the constraining feature includes at least one of a lead and a tie bar of the leadframe.

~~35~~33. The clamping system of claim 20 wherein the constraining feature is configured to constrain the portion of the semiconductor device in at least one direction.

~~36~~34. The clamping system of claim ~~35~~ 33 wherein the at least one direction is a horizontal direction.

~~37~~35. The clamping system of claim ~~35~~ 33 wherein the at least one direction includes a direction of ultrasonic scrubbing of a bonding tool motion of a wire bonding machine.

~~38~~36. The clamping system of claim ~~35~~ 33 wherein the at least one direction includes at least two directions.